ASSOCIATION CONNECTIN	Material Composition © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved untions.	nder both	This docum level parts, t	ent is a declara the declaration	ion of the s encompasse	ubstances es all lower	within the manufacture r level materials for v	rer listed	item. Note: it manufacturer	f the item is an as has engineering	ssembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and N	als and Mfg Information					
Supplier Inform	ation														
Company name*			Company unique ID				Unique ID Authority				Respon	Response Date*			
onsemi											2023-0	2023-06-08			
Contact Name			Title - Contact				Phone - Contact*				Email ·	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email ·	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requeste	er Item Number Mfr Item Nu		Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		FSB5082	5BS	SPM5 V3 INV 250V 0.450hm			2023-06-08		C	СРА		3363.5	mg	Each	
Manufacturing	Proccess Information	n													
Terminal Plating / Grid Array Material Terr			erminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperatu		e Max Time at Peak	K Tempera	ture Numb	er of Reflow Cy	cles			
Matte Tin (Sn) - annealed			U Alloy 3			260 C		С	30 s		nds 3				
Comments															
ATTENTION: MSL	. 3 Rated item requires Ba	ke and D	ry Pack (after	electrical test)											
or more informatio	on regarding material con	position j	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	38.0	mg	Supplier	Silicon (Si)	7440-21-3		38	mg
Die Attach	9.5	mg	Supplier	Silver (Ag)	7440-22-4		7.22	mg
			Supplier	Phenolic Resin-2	54208-63-8		2.28	mg
Die Attach Solder	7.6	mg	Supplier	Silver (Ag)	7440-22-4		0.19	mg
			А	Lead (Pb)	7439-92-1	7a	7.03	mg
			Supplier	Tin (Sn)	7440-31-5		0.38	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1876.0	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		37.52	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		272.02	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		56.28	mg
			Supplier	Carbon Black (C)	1333-86-4		9.38	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1500.8	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	6.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.12	mg
			Supplier	Copper (Cu)	7440-50-8		5.88	mg